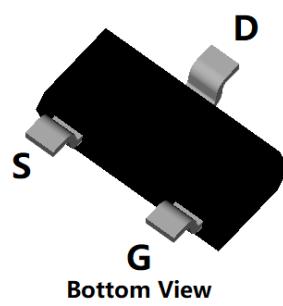
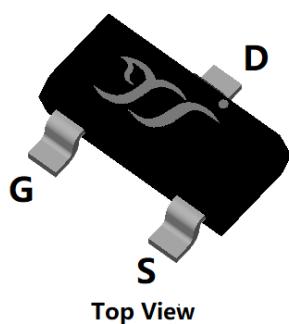
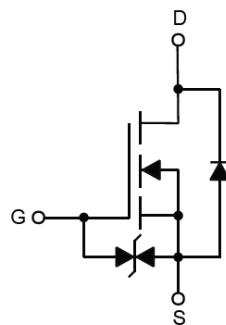




N-Channel Enhancement Mode Field Effect Transistor

**SOT-23**

Product Summary

- V_{DS} 60V
- I_D 300mA
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<2.0\text{ohm}$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<2.5\text{ohm}$
- ESD protected up to 2.0kV (HBM)

General Description

- Trench Power MV MOSFET technology
- Voltage controlled small signal switch
- Low input Capacitance
- Fast Switching Speed
- Low Input / Output Leakage
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Battery operated systems
- Solid-state relays
- Direct logic-level interface: TTL/CMOS
- 12V, 24V Automotive systems

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	60	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current @ $T_A=25^\circ\text{C}$	I_D	300	mA
Pulsed Drain Current ^A	I_{DM}	1.5	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	520	mW
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	285	$^\circ\text{C} / \text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+175	$^\circ\text{C}$

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
2N7002KDHQ	F2	72KD.	3000	30000	120000	7" reel



2N7002KDHQ

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 10	μA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.1	1.5	2.4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=300\text{mA}$		1.1	2.0	Ω
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=200\text{mA}$		1.3	2.5	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=115\text{mA}, V_{\text{GS}}=0\text{V}$		0.9	1.2	V
Gate resistance	R_{G}	$f=1\text{MHz}$		150		Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		25		pF
Output Capacitance	C_{oss}			8		
Reverse Transfer Capacitance	C_{rss}			4		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=30\text{V}, I_{\text{D}}=1\text{A}$		1.75		nC
Gate Source Charge	Q_{gs}			1.00		
Gate Drain Charge	Q_{gd}			0.25		
Reverse Recovery Charge	Q_{rr}	$I_{\text{SD}}=1\text{A}, \text{di/dt}=100\text{A/us}$		3.9		nC
Reverse Recovery Time	t_{rr}			15		ns
Turn-on Delay Time	$t_{\text{D(on)}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=30\text{V}, I_{\text{D}}=1\text{A}, R_{\text{g}}=3\Omega$		4.6		ns
Turn-on Rise Time	t_{r}			20.0		
Turn-off Delay Time	$t_{\text{D(off)}}$			10.5		
Turn-off Fall Time	t_{f}			25.5		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. The value of $R_{\theta JA}$ is measured with the device mounted on the minimum recommend pad size, in the still air environment with $T_A = 25^\circ\text{C}$. The maximum allowed junction temperature of 175°C . The value in any given application depends on the user's specific board design.



2N7002KDHQ

■ Typical Performance Characteristics

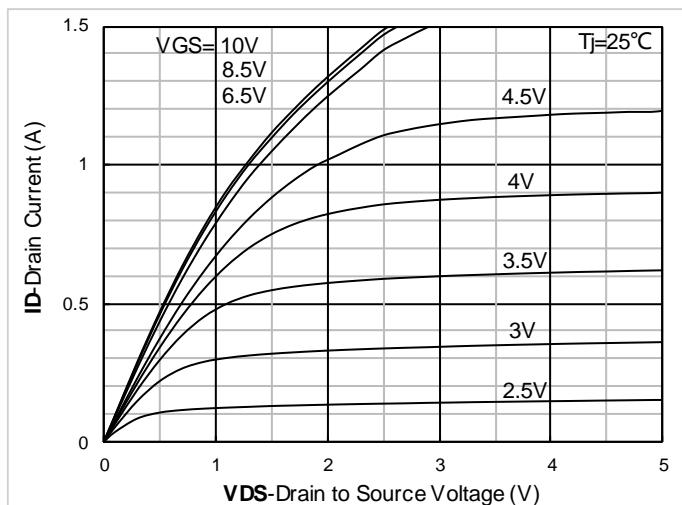


Figure1. Output Characteristics

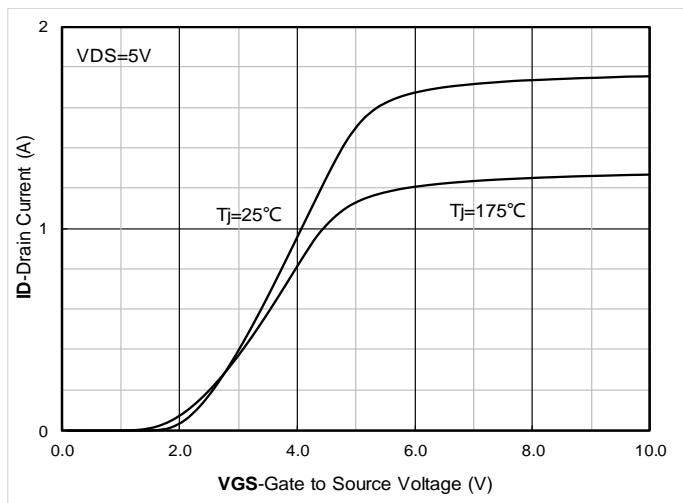


Figure2. Transfer Characteristics

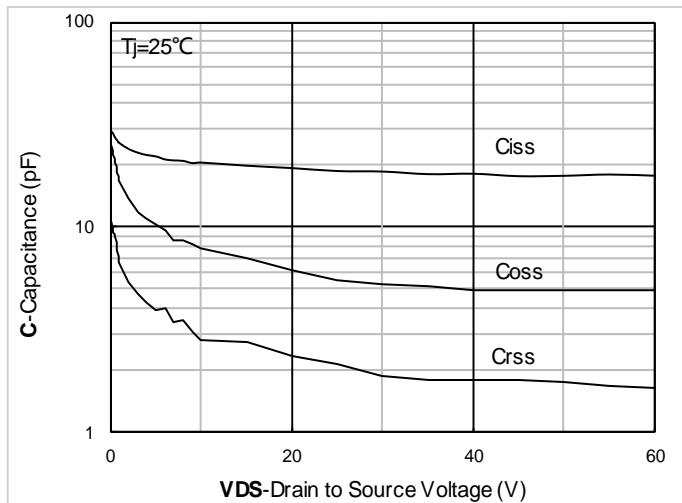


Figure3. Capacitance Characteristics

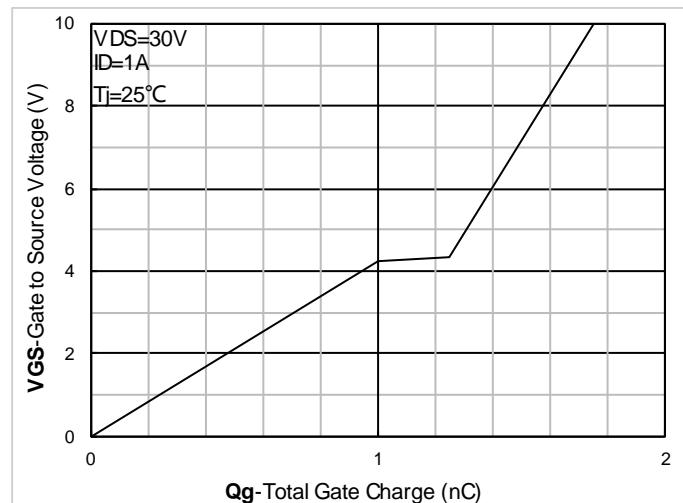


Figure4. Gate Charge

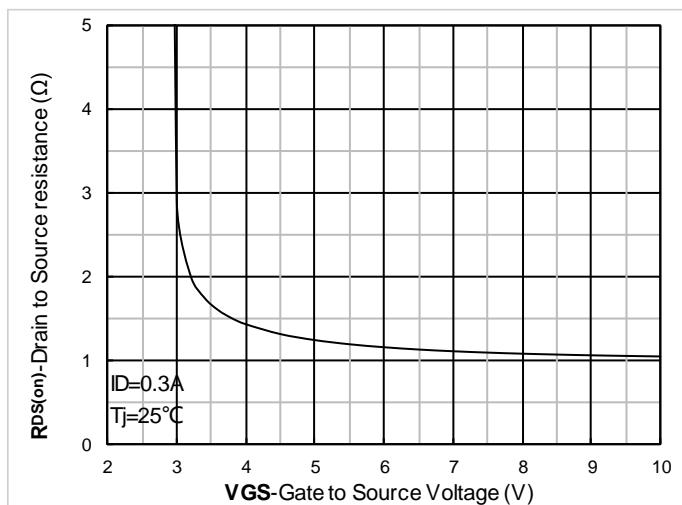


Figure5. On-Resistance vs Gate to Source Voltage

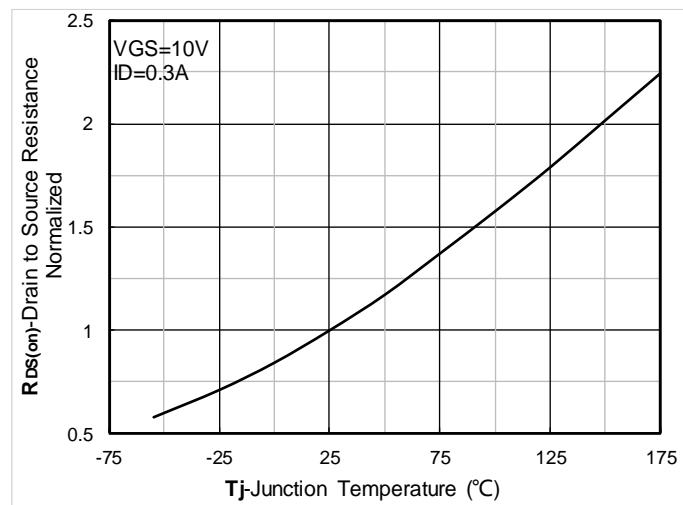


Figure6. Normalized On-Resistance

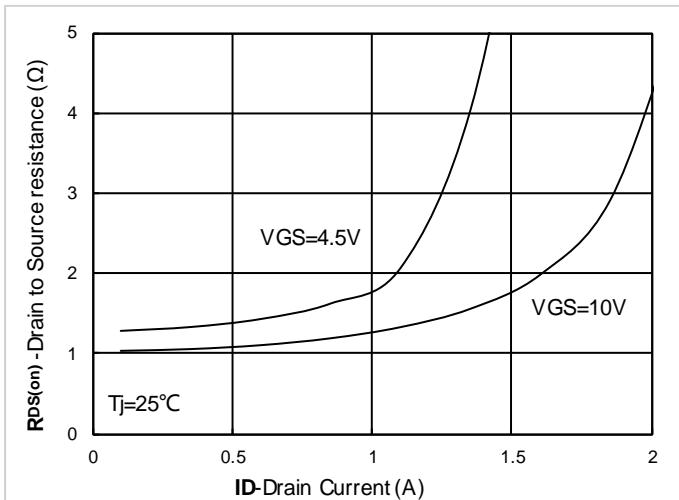
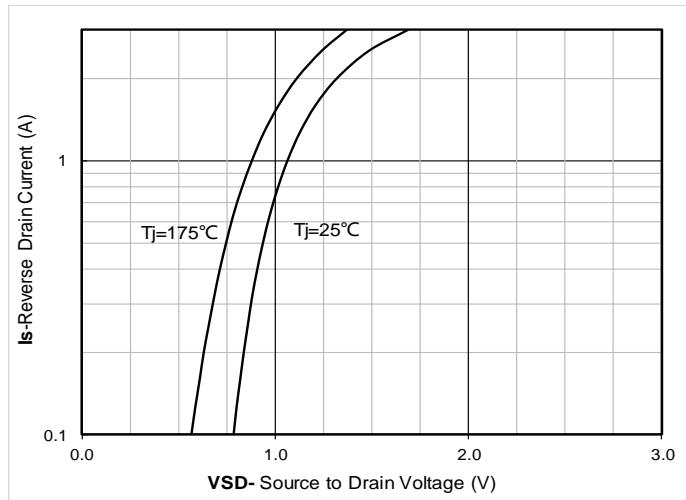
Figure 7. $R_{DS(on)}$ VS Drain Current

Figure 8. Forward characteristics of reverse diode

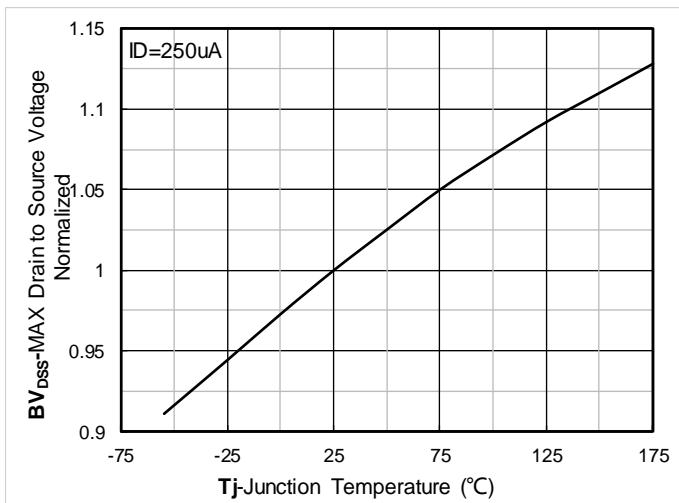


Figure 9. Normalized breakdown voltage

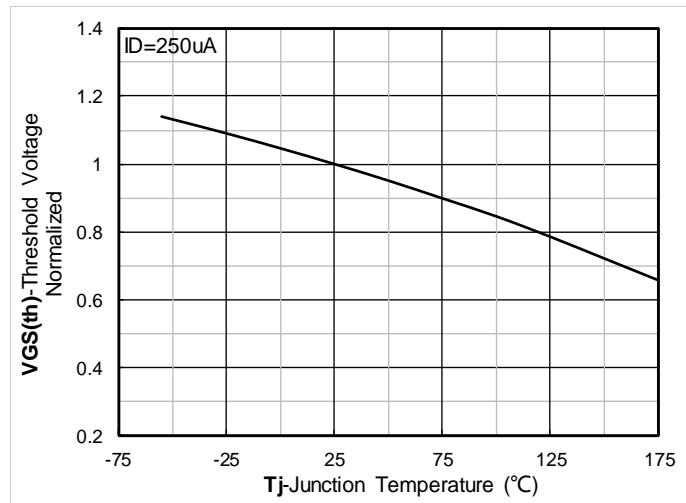


Figure 10. Normalized Threshold voltage

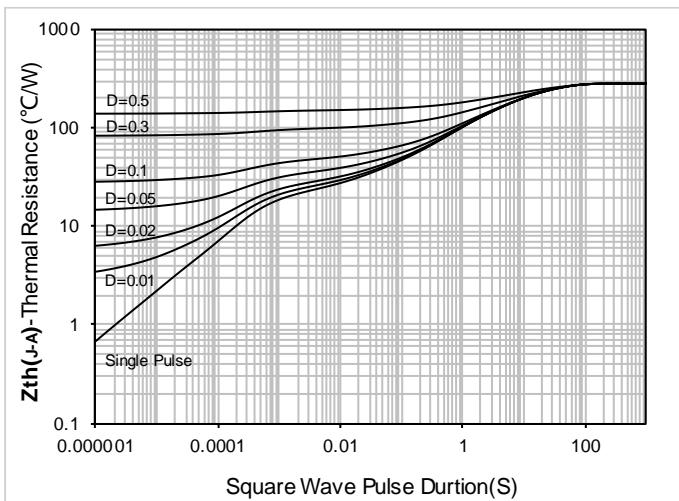


Figure 11. Maximum Transient Thermal Impedance

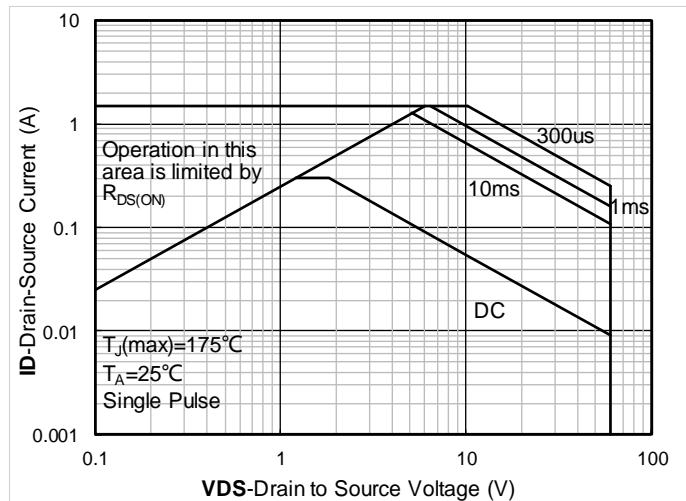


Figure 12. Safe Operation Area

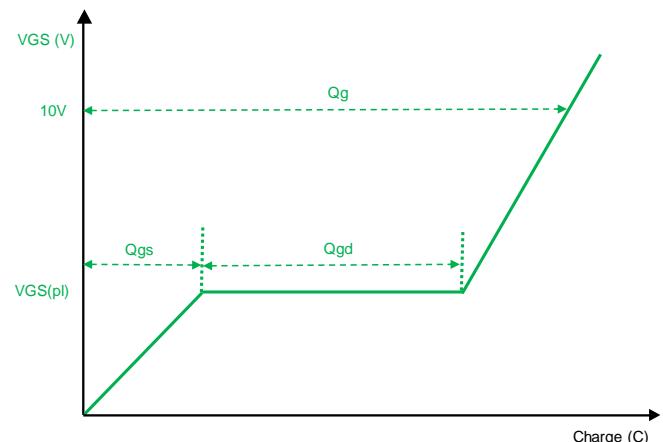
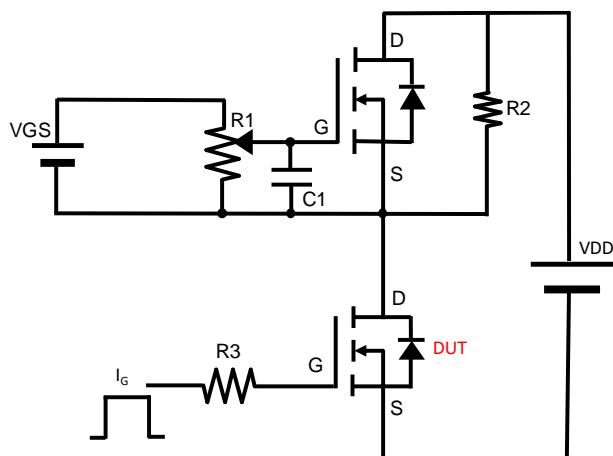
**■ Test Circuits & Waveforms**

Figure A. Gate Charge Test Circuit & Waveform

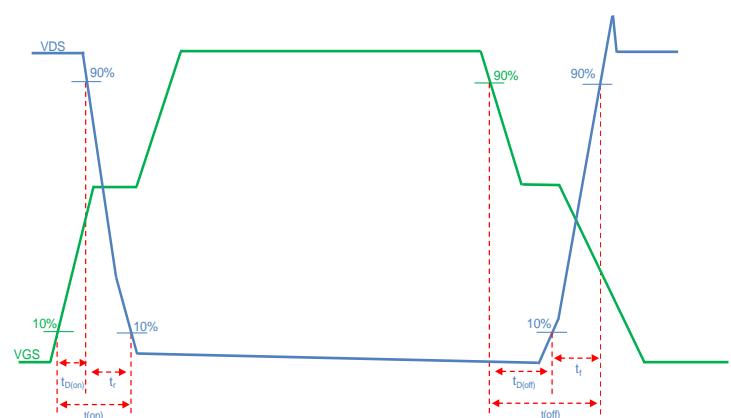
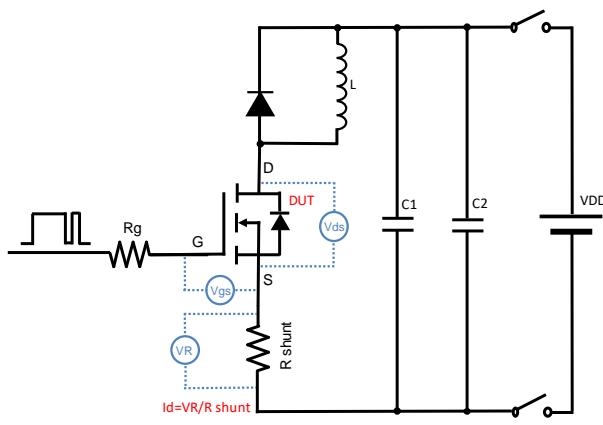


Figure B. Resistive Switching Test Circuit & Waveform

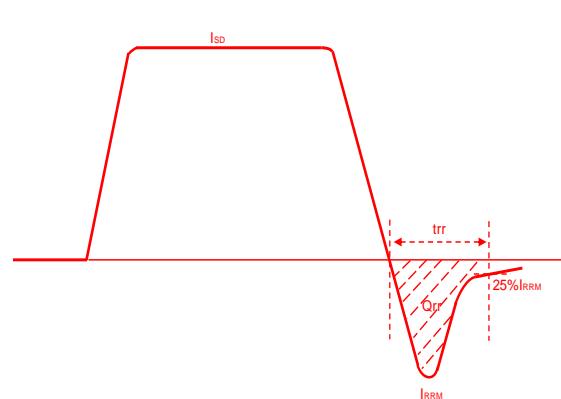
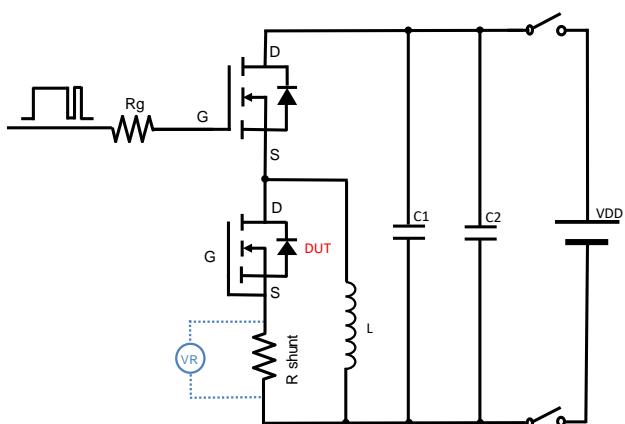
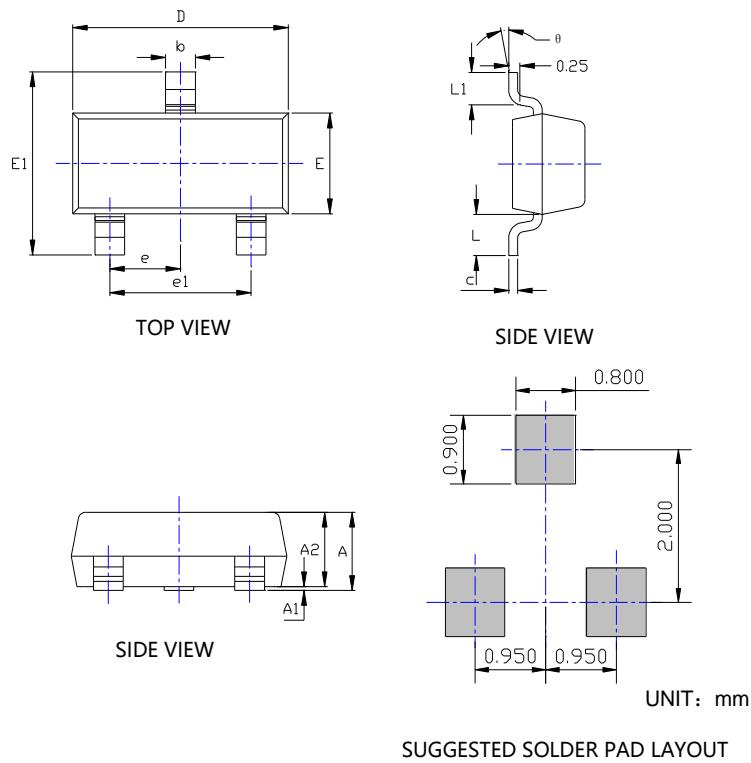
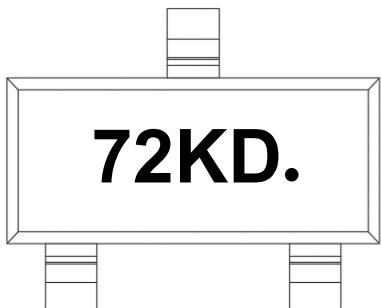


Figure C. Diode Recovery Test Circuit & Waveform

**■ SOT-23 Package Outline Dimensions**

SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
theta	0°	8°	0°	8°

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

■ Marking Information

Note:

1. All marking is at middle of the product body
2. All marking is in laser marking
3. 72KD is Marking Code
4. Body color: Black



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